



Applied Materials Sets New Benchmark for 300mm High-Volume Manufacturing with Applied Endura2 System

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SANTA CLARA, Calif.--(BUSINESS WIRE)--Feb. 17, 2004--Applied Materials, Inc. today launches a new generation of its acclaimed Applied Endura(R) platform, the Applied Endura(R)2. Based on the industry's most successful semiconductor processing system, the Endura2 platform has 20 percent fewer parts and sets a new standard for clean design that emphasizes reliability, serviceability and overall equipment efficiency for 300mm high-volume manufacturing. Its true modular architecture slashes system manufacturing time by one-third, reducing order lead time and shortening startup time in customer fabs.

"Capitalizing on 15 years of experience and learning in PVD technology and an installed base of over 3,000 systems at customer sites worldwide that have processed more than 1 billion wafers, we've redesigned the Endura platform by focusing on technology and time - which are both critical to our customers' business success," said Dr. Fusen Chen, vice president and general manager of Applied Materials' Copper, PVD and Integrated Systems Product Business Group. "The Endura2 is faster and easier to build, enabling us to rapidly respond to customer capacity increases. The simplified design speeds system installation and improves reliability and serviceability by more than 20 percent to provide customers with more 'profit time' on the system."

The Applied Endura2 extends PVD processing for future chip generations while also enabling the integration of leading-edge CVD and ALD technologies. Marathon testing has proven the system's reliability and 45nm-level mechanical defect performance (less than 0.04 defects/cm² at greater than 0.09um), as well as complete transparency for the Endura's full library of advanced process technologies--which require no modification or requalification. Endura2 processes have already been qualified for 90nm and 65nm device nodes and are in R&D for 45nm.

The Endura2 platform includes Applied Materials' high-speed XP dual-wafer robotic handling technology that boosts platform throughput, plus new, easily serviced component modules that enhance availability and contribute to the system's real-world 300 hour reliability (MTBF*) and less than 2 hour repair time (MTTR*).

Applied Materials, Inc. (Nasdaq:AMAT) is the largest supplier of equipment and services to the global semiconductor industry. Applied Materials' Web site is <http://www.appliedmaterials.com>

*PVD: physical vapor deposition

MTBF: mean time between failure

MTTR: mean time to repair

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